

EMI Common Mode Choke



BWCC Series



Overview

An EMI common mode choke (CMC) for power lines is a passive component specifically designed to suppress electromagnetic interference (EMI) in power supply circuits. A full series of common mode choke is designed for excellent noise attenuation with compact sizing for use in wide range of applications. Both standard series and custom designs are available.

Benefits

1. EMI/RFI Suppression
2. Miniature SMD type common mode filter for fully automated assembly
3. Excellent solderability

Applications

1. USB line for personal computers and peripheral
2. IEEE 1394 line for personal computers, DVC, STB
3. LVDS, panel line for liquid display panels, graph card, etc

Product Information

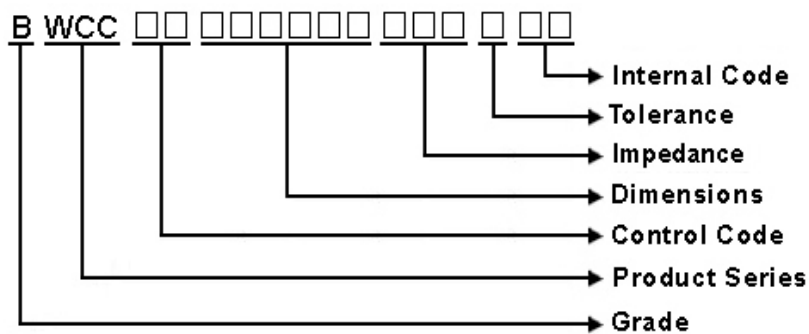
Series	Size Code (JIS/EIA)	Impedance(Ω)
BWCC	2012/0805	30 ~ 260



BWCC00201208 Series Specification

1 Scope: This specification applies to BWCC Wire Wound Common Mode Choke Coil

2 Part Numbering:



3 Rating:

Operating Temperature: - 40°C ~ 105°C
(Including self - temperature rise)

Storage Temperature: - 40°C ~ 105°C
(The storage temperature range is for after the assembly)

4 Marking:

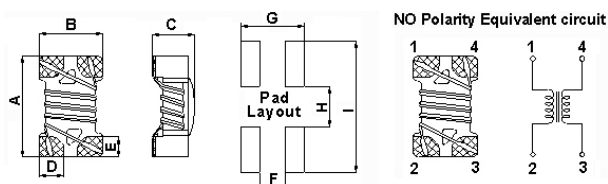
No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

BWCC00201208 Series Specification

6 Configuration and Dimensions and Unit Weight:



Dimensions in mm

TYPE	A	B	C	D	E	F	G	H	I
201212	2.0±0.2	1.2±0.2	0.8±0.2	0.50	0.40	0.5	1.27	1.1	2.6

Net Weight (grms)

SIZE CODE	Net Weight (grms)
201212	0.008 (typ.)

7 Electrical Characteristics:

Part No.	Z (Ω)	RDC (Ω)Max.	IDC (mA)	Rated Voltage (Vdc)	Withstanding Voltage (Vdc)	Insulation Resistance (MΩ)(min)	Tolerance (±%)	Test Freq. (MHz)
BWCC00201208300□02	30	0.2	1300	50	125	10	20	100
BWCC00201208420□02	42	0.2	1300	50	125	10	20	100
BWCC00201208670□02	67	0.25	1200	50	125	10	20	100
BWCC00201208900□02	90	0.27	1000	50	125	10	20	100
BWCC00201208121□02	120	0.3	900	50	125	10	20	100
BWCC00201208181□02	180	0.4	700	50	125	10	20	100
BWCC00201208261□02	260	0.6	700	50	125	10	20	100

NOTE: □-tolerance M=±20%

1. Operating temperature range - 40 °C ~ 105 °C (Including self - temperature rise)

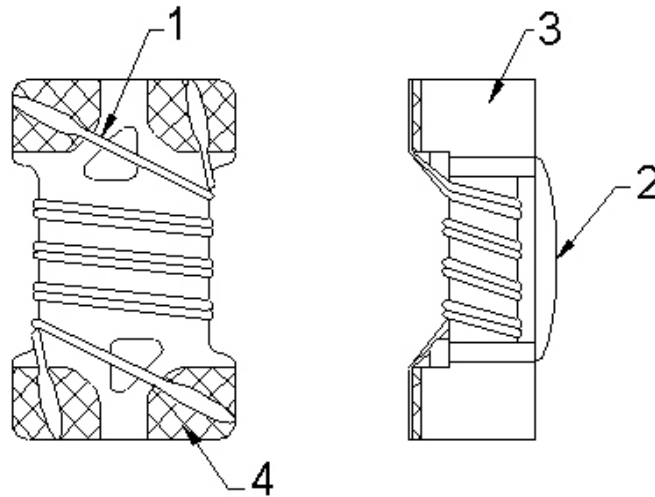
2. RDC: SINGLE WIRE TEST VALUE

3. IDC for Inductance drop 10% from its value without current.

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8 BWCC00201208 Series

8.1 Construction:



8.2 Material List:

NO	PART	MATERIAL
1	WIRE	Grade 180
2	EPOXY	UV GLUE
3	CORE	FERRITE CORE
4	TERMINAL	Ag/Cu/Ni/Sn

BWCC00201208 Series Specification

9 Common Mode Choke / RELIABILITY TEST

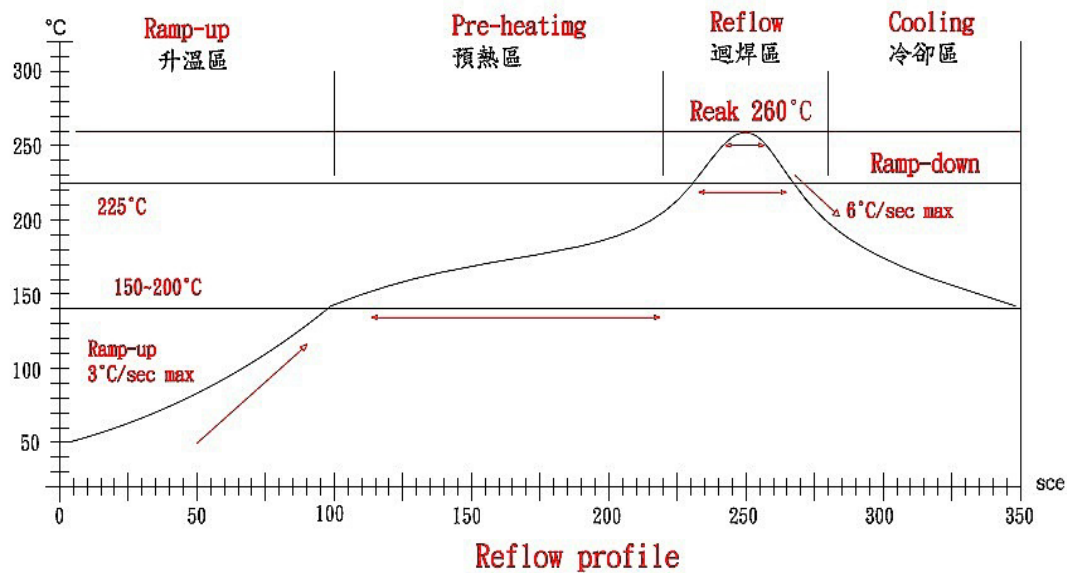
1-1.Environmental Performance

1- Environmental Performance					
No	Item	Specification	Test Method		
1-1-1	Temperature Cycle	Appearance: No Damage Impedance: within±20% of initial value	One cycle:		
			Step	Temperature (°C)	Time (min)
			1	-40±3	30
			2	25±2	3
			3	105±3	30
			4	25±2	3
			Total: 5 cycles		
Measured After Exposure in The Room Condition For 1hrs					
1-1-2	High Temperature Resistance		Temperature: 105±3℃ Time: 1000Hrs Measured After Exposure In The Room Condition For 1Hrs		
1-1-3	Low Temperature Resistance		Temperature: -40±3℃ Time: 1000Hrs Measured After Exposure In The Room Condition For 1Hrs		
1-1-4	Humidity Load Life	There should be no evidence of short or open circle	Temperature: 40±2℃ Relative Humidity: 90~95% Load: Allowed DC Current Time: 96Hrs		

1-2.Mechanical Performance

No	Item	Specification	Test Method
1-2-1	Resistance To Soldering Heat	Appearance: No Damage	1. The device should be reflow soldered on PCB (peak $260^{\circ}\text{C}\pm 5^{\circ}\text{C}$ for 10 seconds) 2. Solder Composition: Sn/Ag3.0/Cu0.5 3. Test time: 6 minutes
1-2-2	Solder ability	The electrodes shall be at least 95% covered with new solder coating	1. Pre-Heating: 150°C , 1min. 2. Solder Composition: Sn/Ag3.0/Cu0.5 3. Solder Temperature: $245\pm 5^{\circ}\text{C}$. 4. Immersion Time: 4 ± 1 sec.
1-2-3	Commponent Adhesion (Push Test)	1 Lbs. For 1210 Size 2 Lbs. For other	The device should be reflow soldered ($245\pm 5^{\circ}\text{C}$ For 10 seconds) to a tinned copper substrate. A force guauge should be applied to the side of the component. The device must withstand a minimum force of 2 pounds without a failure of the termination attached to component

BWCC00201208 Series Specification



Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升温區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150°C	150°C ~ 200°C	Above 217°C	260±5°C	Peak Temp.~150°C
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	-	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	-

NOTE:

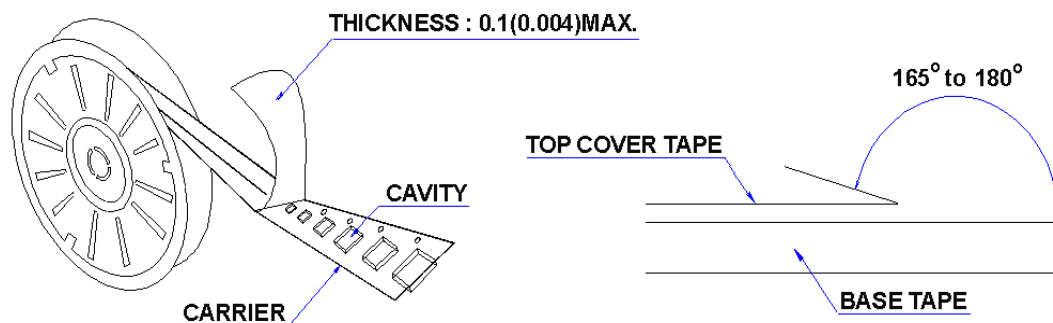
- 1.Re-flow possible times : within 3 times
- 2.Nitrogen adopted is recommendes while in re-flow
- 3.Products can only be soldered with reflow

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10 Packaging:

10.1 Packaging -Cover Tape

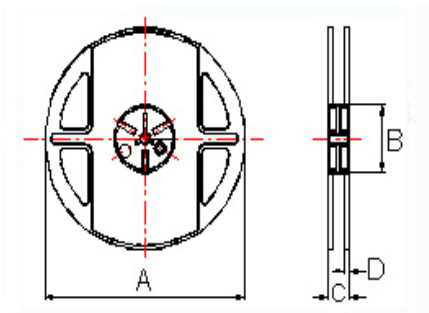
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



10.2 Packaging Quantity

TYPE	PCS/REEL
201208	2000

10.3 Reel Dimensions



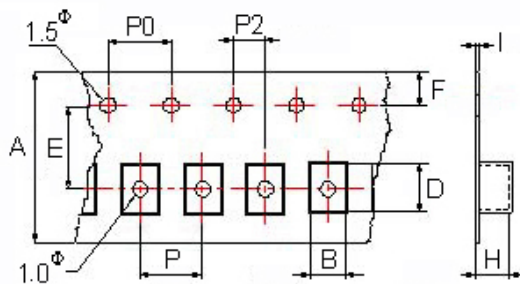
Dimensions in mm

TYPE	A	B	C	D
201208	178±1	60±0.5	12±0.5	1.5±0.5

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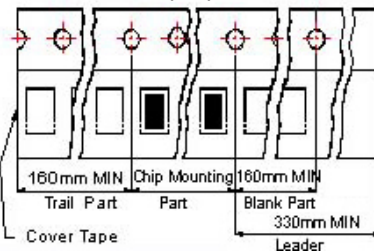
10 Packaging:

10.4 Tape Dimensions in mm



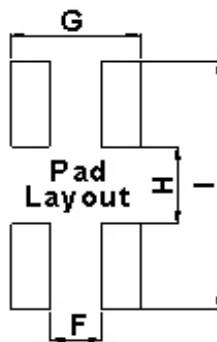
Tape Material

Carrier tape : Polycarbonate
Cover tape : Polyethylene



TYPE	A	B	D	E	F	H	I	P	P0	P2
201208	8	1.4	2.3	3.5	1.75	1.1	0.2	4	4	2

11 Recommended Land Pattern:



Dimensions in mm

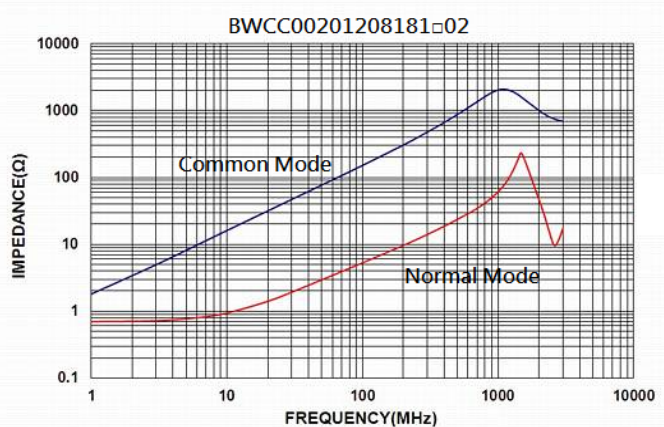
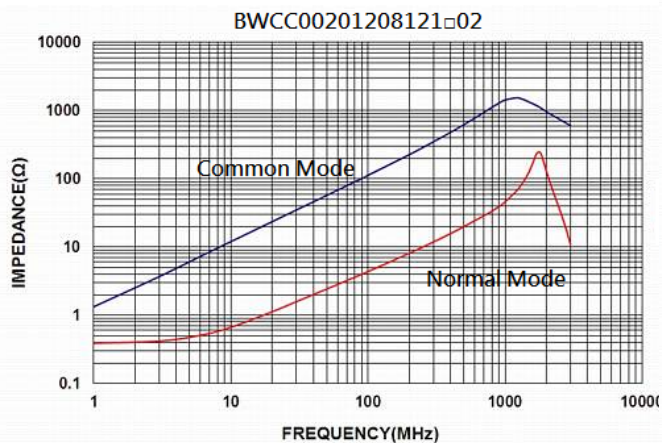
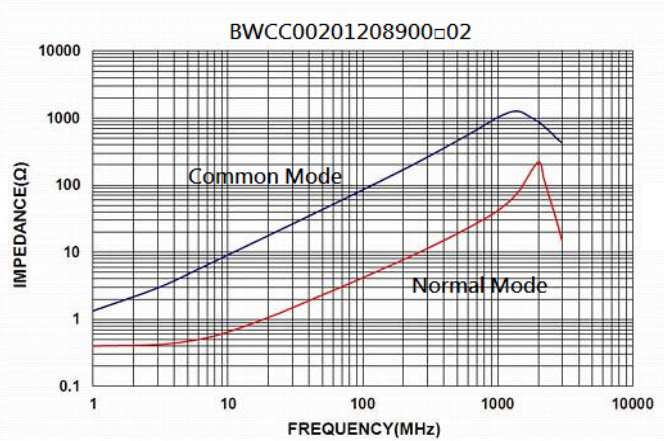
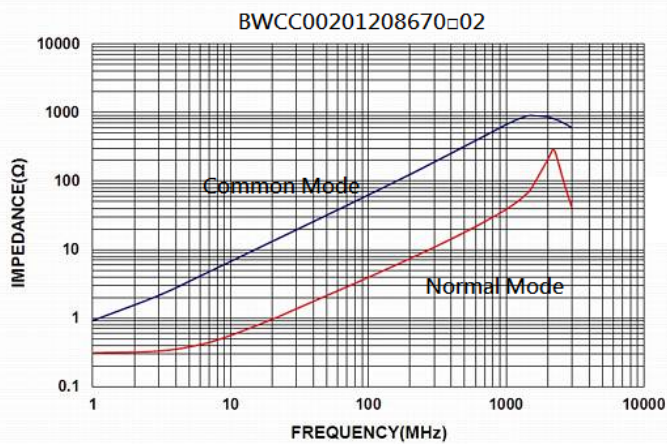
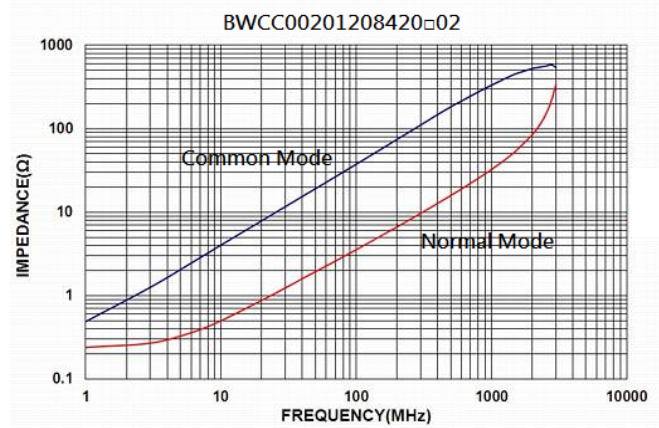
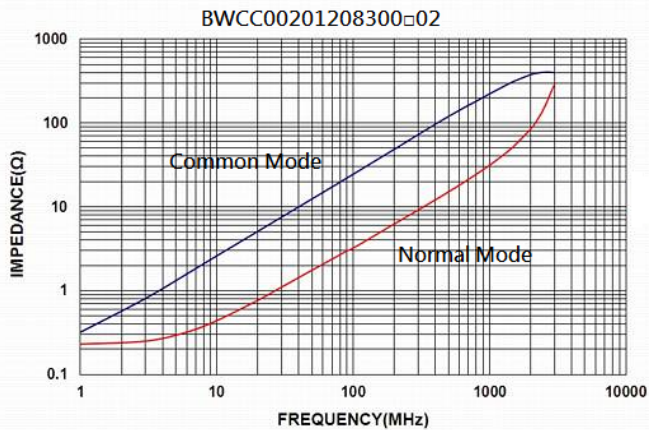
TYPE	F(In/mm)	G(In/mm)	H(In/mm)	I(In/mm)
201208	0.020/0.5	0.05/1.27	0.03/1.1	0.10/2.6

12 Note:

- Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- Do not knock nor drop.
- All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- The storage period is less than 12 months. Be sure to follow the storage conditions (Temperature: 5 to 40°C, Humidity: 10 to 75% RH or less).
If the storage period elapses, the soldering of the terminal electrodes may deteriorate.
- Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
- The moisture sensitivity level (MSL) of products is classified as level 1.

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13 Graph:



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